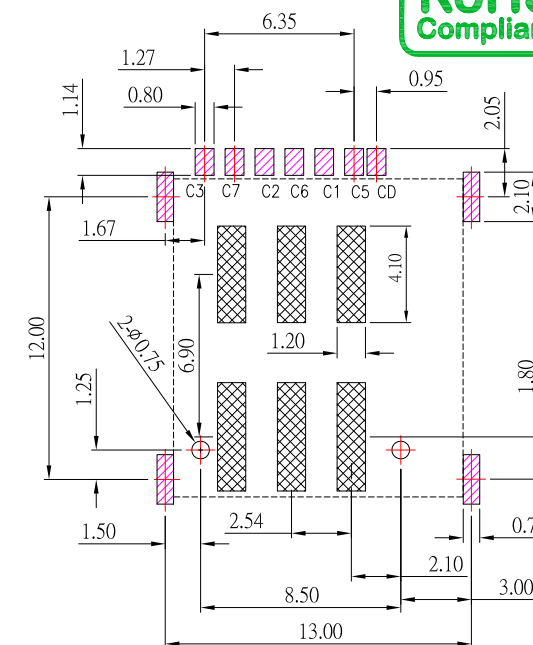
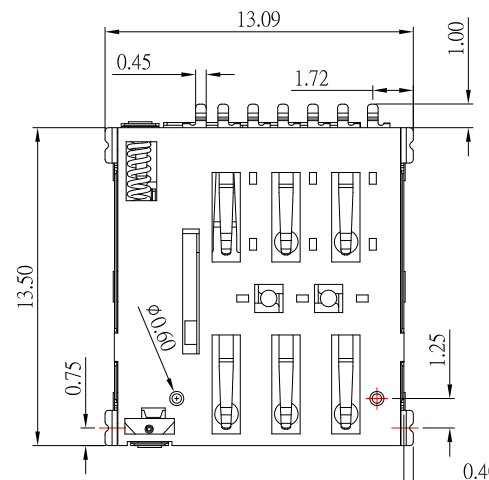
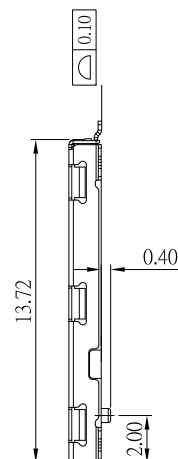
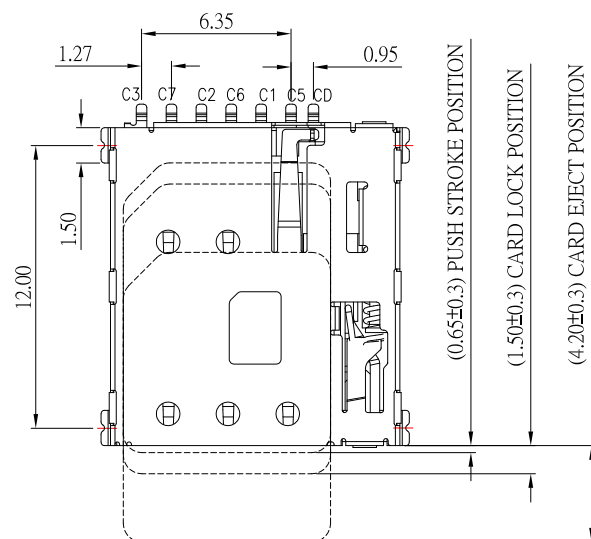
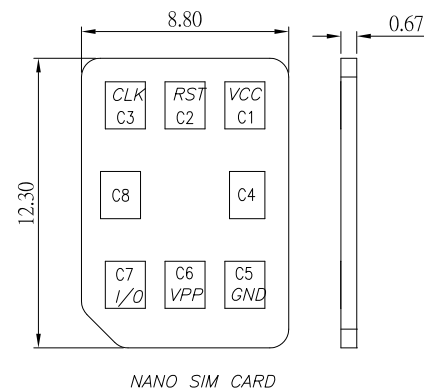
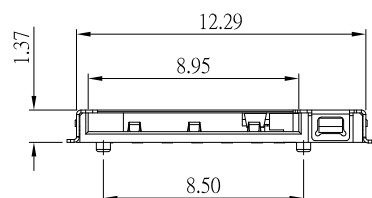
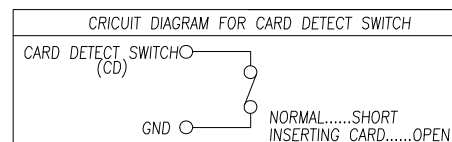




P.C.B LAYOUT MOUNTING PATTERN



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



MATERIALS:

- HOUSING : HIGH TEMPERATURE THERMOPLASTIC
- TERMINAL : COPPER ALLOY
- SHELL : SUS

Finish:

- Finish: CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- SHELL: NICKEL UNDER PLATED SURFACE LAYER

SPECIFICATION:

- RATING : 0.5 mA , 125V AC / DC
- DIELECTRIC WITHSTANDING VOLTAGE : 500V AC
- INSULATION RESISTANCE : 1000MΩ MIN.
- CONTACT RESISTANCE : 100mΩ MAX.
- OPERATING TEMPERATURE : -20°C TO +60°C.



东莞市高迪电子有限公司
Dong Guan KDRR Electronic Switch Jack Co., Ltd.

TOLERANCE UNLESS
OTHERWISE STATED :

Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3

3RD.
ANGEL'S



UNITS

MM

DRAWN BY: Jack Lu
CHECKED BY: Jacky Chen
APPROVED BY: Tony Kao

DATE
05/28/19
DATE
05/28/19
DATE
05/28/19

MAT'L	TITLE	CONNECTOR
FINISH	MODLE	Nano SIM CARD SOCKET 6PIN 1.35H
SCALE	DWG NO.	NSIM-510010632S-S304
SHEET NO.	PART NO.	NSIM-510010632S-S304

ITEM NO	DESCRIPTION	DRAWN	DATE
3	更新圖面	Jack	052819
2	新增尺寸	Jack	052019
1	新增線路標示	Jack	051419